CALL FOR PAPERS

The 13th International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP 2012) will be held in **Guilin, China, from August 13 to 16, 2012**. The ICEPT-HDP 2012 is organized by Electronic Manufacturing and Packaging Technology Society (EMPT) of Chinese Institute of Electronics (CIE) and co-organized by Guilin University of Electronic Technology. As one of the most famous international conferences on electronic packaging technology, the conference has received strong support from IEEE CPMT and active involvement from IMAPS, ASME and iNEMI, and was highly appreciated by China Institute of Electronics and China Association for Science and Technology (CAST).

ICEPT-HDP 2012 is a four-day event, featuring technical sessions, invited talks, professional development courses/forums, exhibition, and social networking activities. It aims to cover the latest technological developments in electronic packaging, manufacturing and packaging equipment, and provide opportunities to explore the trends of research and development, as well as business in China. We are looking forward to receiving your papers and meeting you at the conference.

CONFERENCE THEMES

- **Advanced Packaging & System Integration:** BGA, CSP, flip chip; WLP, SiP; TSV, 3D integration; and other advanced packaging and system integration technologies.
- **Packaging Materials & Processes:** Green materials, nano-materials and other novel materials for packaging performance enhancement and cost reduction; and various new packaging/assembly processes.
- **Packaging Design and Modeling:** New packaging/assembly designs; methodologies for modeling, simulation and validation of electrical, thermal, optical and mechanical performance of various electronics packages; multi-scale and multi-physics modeling.
- **High Density Substrate & SMT**: Substrate with embedded passives and active components; HDI substrate, PCB, high performance multilayer substrate; and various novel assembly technologies that improve substrate density and performance.
- **Advanced Manufacturing Technologies and Packaging Equipment:** Advanced packaging/assembly related equipment; measurement techniques. Advanced manufacturing technologies for manufacturability and yield improvement, cost reduction and service performance improvement
- **Quality & Reliability:** Quality monitoring and evaluation; methodologies for accelerated reliability data collection and analysis, reliability modeling and life prediction; failure analysis and nondestructive diagnose.
- **Solid State Lighting Packaging & Integration:** CoB, WLP and other advanced packaging/integration technologies; methodologies for design, manufacturing and testing of high power LED module; LED packaging/integration technologies and their applications in LCD, micro-projector, in-door lighting, street lamp, etc.
- **Emerging Technologies**: Packaging technologies for sensors, actuators, MEMS, NEMS and MOEMS; optoelectronics packaging; packaging/integration technologies and their applications in LCD, passive & RF devices, power & HV devices, nano-devices, etc.

IMPORTANT DATES

- **March 16, 2012** Deadline for Submission of Abstract
- **April 10, 2012** Notification of Acceptance
- **June 22, 2012** Deadline for Submission of Manuscript

SUBMISSION OF ABSTRACT

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, conclusions, and important references of the work. All abstracts must be in English and should be submitted using the format provided in the attached word file to icept2012@vip.163.com.

The template for abstract submission can be downloaded at the conference website http://www.icept.org. Selected papers will be recommended for publication in IEEE/CPMT journals.

BEST CONFERENCE PAPERS AND BEST STUDENT PAPERS

The conference proceeding is an official IEEE publication. Best Conference and Student Papers will be selected and awarded at the conference.

CALL FOR PROFESSIONAL DEVELOPMENT COURSES

The conference program includes professional development courses (PDC), the leading experts in the field may email icept2012@vip.163.com for details.

CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components, software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may email to: faith_epe@shou.net for details.

General Chair: Prof. Keyun BI
Organization Chair: Prof. Kailin PAN
Technical Chair: Prof. Daoguo YANG
Conference Website: http://www.icept.org
Conference Email: icept2012@vip.163.com

ABOUT Guilin

Located in the northeast of Guangxi Zhuang Autonomous Region, Guilin has a long history as the most beautiful place in China, famous for its wonderful scenery, crystal clear waters, unique caves, beautiful stones and karst peaks covered in lush greenery. Major attractions include Elephant Trunk Hill, Li River, Reed Flute Cave and Seven-Star Park, etc. A trip along the Li River is one of the highlights of a holiday in China. From Guilin to Yangshuo, the river meanders its way through 83 kilometers of beautiful countryside, with bamboo forests, dense reed-beds, and incredibly bizarre rock formations.

Organized by CIE, EMPT — CIE--Electronic Manufacturing and Packaging Technology Society

Supported by IEEE, CPMT — IEEE COMPONENTS, PACKAGING AND MANUFACURING TECHNOLOGY SOCIETY

Co-organized by 桂林電子科技大學 GUILIN UNIVERSITY OF ELECTRONIC TECHNOLOGY